

### **Features**

- Trench Power LV MOSFET technology
- · AEC-Q101 Qualified
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

# **Maximum Ratings**

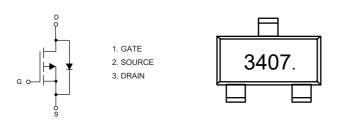
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 96°C/W Junction to Ambient<sup>(Note 2)</sup>

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage	V <sub>DS</sub>	-30	V		
Gate-Source Volltage		$V_{GS}$	±20	V	
Continuous Drain Current	T <sub>A</sub> =25°C		-4.1	Α	
	T <sub>A</sub> =70°C	- I <sub>D</sub>	-3.2		
Pulsed Drain Current(Note 3)		I <sub>DM</sub>	-12	Α	
Total Power Dissipation(Note 4)		P <sub>D</sub>	1.3	W	

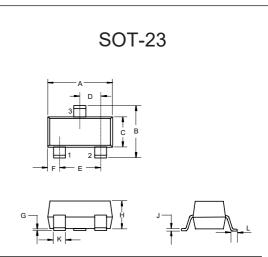
### Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of  $R_{\theta JA}$  is measured with the device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$  =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. Pd is based on max. junction temperature, using junction-case thermal resistance.

# **Internal Structure and Marking Code**

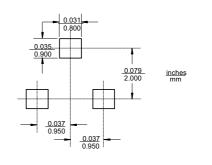


# P-CHANNEL MOSFET



DIMENSIONS					
DIM	INC	HES	MM		NOTE
DIIVI	MIN	MAX	MIN	MAX	NOTE
Α	0.110	0.120	2.80	3.04	
В	0.083	0.104	2.10	2.64	
С	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
Н	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

### **Suggested Solder Pad Layout**



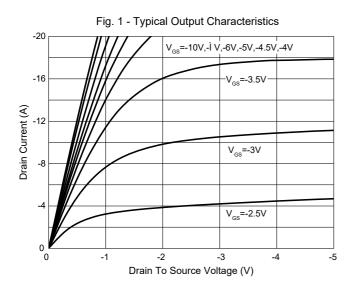


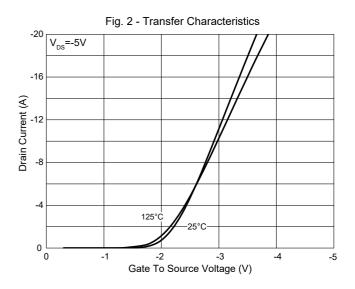
# Electrical Characteristics @ 25°C (Unless Otherwise Specified)

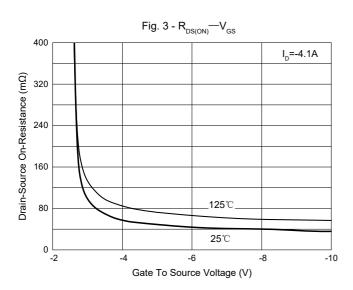
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250µA	-30			V	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			-1	μA	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1	-1.5	-2.4	V	
Drain-Source On-Resistance	В	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.1A			49	mΩ	
	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.2A			65		
Diode Characteristics							
Continuous Body Diode Current	Is				-4.1	Α	
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-4.1A			-1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	L = 2.24 di/dt=1004/up		12		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>S</sub> =-2.2A,di/dt=100A/μs		3.6		nC	
Dynamic Characteristics							
Input Capacitance	C <sub>iss</sub>			592			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V,f=1MHz		73		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			63		1	
Total Gate Charge	$Q_g$			13			
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =-15V,V <sub>GS</sub> =-10V,I <sub>D</sub> =-4.1A		1.5		nC	
Gate-Drain Charge	$Q_{gd}$			2.2			
Turn-On Delay Time	t <sub>d(on)</sub>			6.2			
Turn-On Rise Time	t <sub>r</sub>	$V_{DS}$ =15V, $V_{G}$ =10V, $R_{G}$ =4.5 $\Omega$ , $I_{D}$ =20A		3.8		- ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	11G-4.012, 1D-2011		23			
Turn-Off Fall Time	t <sub>f</sub>			9.4			

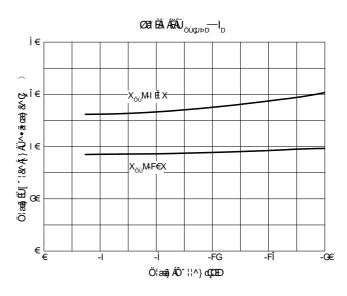


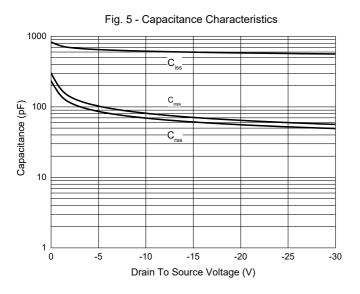
# **Curve Characteristics**

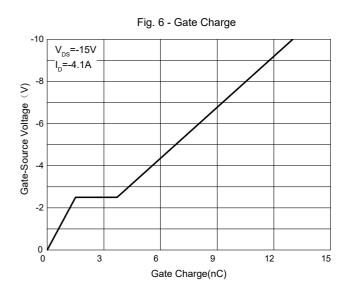






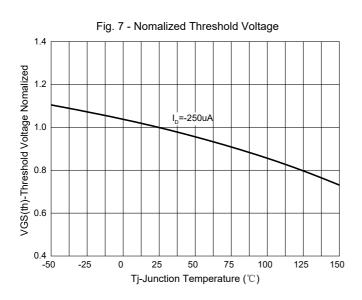


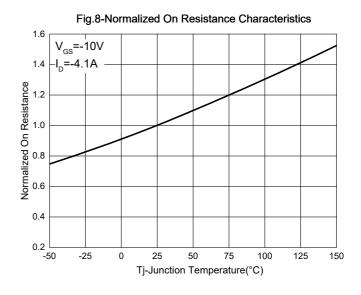


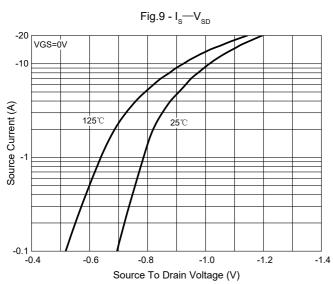


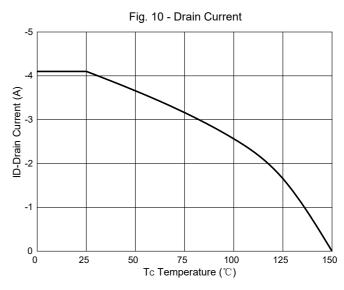


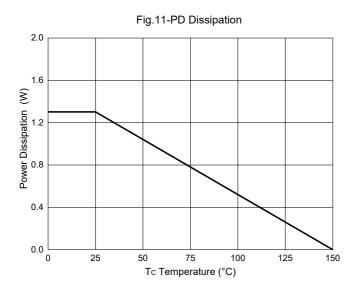
# **Curve Characteristics**





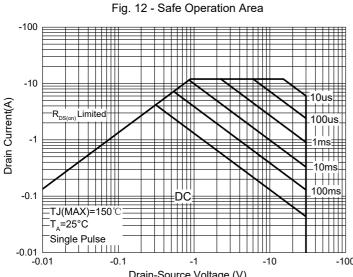






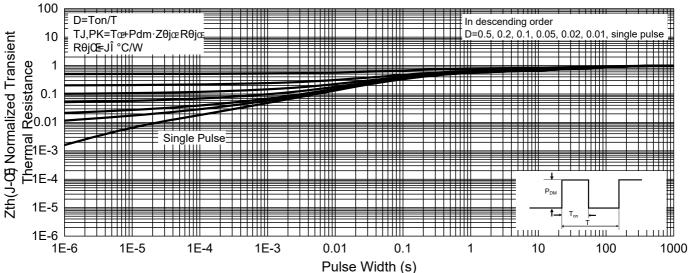


## **Curve Characteristics**



-100 Drain-Source Voltage (V)

Fig. 13 -Normalized Transient Thermal Impedance





# **Ordering Information**

Device	Packing
SI3407HE3-TP	Tape&Reel: 3Kpcs/Reel

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